

67,200-591  
2001-0289

ABSTRACT OF THE DISCLOSURE

0073        A method of forming a bump on a substrate such as a semiconductor wafer or flip chip. The method includes the act of providing a semiconductor device having a contact pad and having an upper passivation layer and an opening formed in the upper passivation layer exposing a portion of the contact pad. An under bump metallurgy is deposited over the upper passivation layer and the contact pad. An electrically conductive redistribution trace is deposited over the under bump metallurgy. A photoresist layer is deposited, patterned and developed to provide portions selectively protecting the electrically conductive redistribution trace and the under bump metallurgy. Excess portions of the electrically conductive redistribution trace and under bump metallurgy not protected by the photoresist are removed.